

Title (en)  
METHOD FOR PRODUCING A SMARTCARD BODY FOR RECEIVING A SEMICONDUCTOR CHIP AND SMARTCARD BODY OF THIS TYPE

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES SMARTCARD-KÖRPERS ZUR AUFNAHME EINES HALBLEITER-CHIPS SOWIE EIN DERARTIGER SMARTCARD-KÖRPER

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN CORPS DE CARTE À PUCE DESTINÉ À RECEVOIR UNE PUCE DE SEMI-CONDUCTEUR, ET CORPS DE CARTE À PUCE CORRESPONDANT

Publication  
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Application  
**EP 13725060 A 20130425**

Priority

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Abstract (en)  
[origin: WO2013159929A1] The invention relates to a method for producing a smartcard body for receiving a semiconductor chip, at least one leadframe (11) of the smartcard body (10) being formed in a substrate material (100), the leadframe being connected via at least one material strip (15) to the substrate material (100), and in which an electrically insulating housing (13) having a cavity (14) to receive the semiconductor chip is formed by the leadframe (11) for forming the smartcard body (10) being surrounded by the housing (13). According to the invention, before or during the formation of the housing (13), the material strip or strips (15) connecting the leadframe (11) to the substrate material (100) is or are severed, by which means the material strip or strips (15) is/are each separated into a first strip part (15a) connected to the substrate material (100) and a second strip part (15b) connected to the leadframe (11), forming an interspace (16), and that, during the formation of the housing (13), both the first strip part (15a) and the second strip part (15b) of the material strip or strips (15) are enclosed by said housing (13).

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